Table I. HEXFET III Die (Continued)

HEX Size	Part Number	V_{DS}	$R_{DS(on)}$ Max	Die (1) Outline Figure	Recomm. Source Bonding Wire mils	Recomm. Source Bonding Wire mm	Equivalent Device Type
P-Channel HEXFETs							
1	IRFC9014	-60	0.500	D33	5	0.13	IRFR9014
1	IRFC9110	-100	1.200	D34	5	0.13	IRF9510
1	IRFC9210*	-200	3.000	D35	5	0.13	IRF9610
2	IRFC9024	-60	0.280	D36	10	0.25	IRF9Z24
2	IRFC9120	-100	0.600	D37	8	0.20	IRF9520
2	IRFC9220*	-200	1.500	D38	8	0.20	IRF9620
3	IRFC9034	-60	0.140	D39	12	0.30	IRF9Z34
3	IRFC9130	-100	0.300	D40	10	0.25	IRF9530
3	IRFC9230	-200	0.800	D41	8	0.20	IRF9630
4	IRFC9044	-60	-	-	20	0.51	-
4	IRFC9140	-100	0.200	D42	15	0.38	IRF9540
4	IRFC9240	-200	0.500	D43	15	0.38	IRF9640
Logic Level Die							
1	IRLC014	60	0.200	D2	5	0.13	IRLZ14
1	IRLC110	100	0.540	D3	5	0.13	IRL510
2	IRLC024	60	0.100	D6	10	0.25	IRLZ24
2	IRLC120	100	0.270	D7	8	0.20	IRL520
3	IRLC034	60	0.050	D12	15	0.38	IRLZ34
3	IRLC130	100	0.160	D13	10	0.25	IRL530
4	IRLC044	60	0.028	D18	20	0.51	IRLZ44
4	IRLC140	100	0.077	D20	15	0.38	IRL540

HEX Size	Part Number	V_{DS}	$R_{DS(on)}$ Max	Nominal Sense Ratio	Die (1) Outline Figure	Recomm. Source Bonding Wire mils	Recomm. Source Bonding Wire mm	Equivalent Device Type
HEXSense Die								
2	IRCC024	60	0.100	780	D44	10	0.25	IRCZ24
3	IRCC034	60	0.050	1410	D45	15	0.38	IRCZ34
3	IRCC130	100	0.160	1430	D46	10	0.25	IRC530
3	IRCC230	200	0.400	1490	D46	8	0.20	IRC630
3	IRCC234	250	0.450	1490	D46	8	0.20	IRC634
3	IRCC330	400	1.000	1525	D46	8	0.20	IRC730
3	IRCC430	500	1.500	1520	D46	8	0.20	IRC830
4	IRCC044	60	0.028	2590	D47	20	0.51	IRCZ44
4	IRCC140	100	0.077	2680	D48	15	0.38	IRC540
4	IRCC240	200	0.180	2740	D48	15	0.38	IRC640
4	IRCC244	250	0.280	2770	D48	15	0.38	IRC644
4	IRCC340	400	0.550	2800	D48	12	0.30	IRC740
4	IRCC440	500	0.850	2780	D48	12	0.30	IRC840
5	IRCC054	60	0.014	2200	D49	25	0.64	IRCP054
5	IRCC150	100	0.055	(5440)	D50	20	0.51	-
5	IRCC250	200	0.085	(5680)	D50	20	0.51	-
5	IRCC254	250	0.140	(5440)	D50	20	0.51	-
5	IRCC350	400	0.300	(5440)	D50	20	0.51	-
5	IRCC450	500	0.400	(5440)	D50	20	0.51	-

*GEN I design

Numbers in parentheses are preliminary.

For more detailed information, please refer to the most current data sheet.

Recommended wire size for Gate, Kelvin and Current Sense connections:
3 to 5 mils (0.076 to 0.127 mm)

(1) For case outline drawing see page O-2.

Common characteristics:

I_{DSS} @ V_{DS} : 250 µA
I_{GSS} : 500 nA
$V_{GS(th)}$: Standard HEXFETs min 2V, max 4V with $V_{DS} = V_{GS}$, ID = 250 µA
$V_{GS(th)}$: Logic level HEXFETs min 1V, max 2V with $V_{DS} = V_{GS}$, ID = 250 µA
$R_{DS(on)}$: Measured with VGS = 10V on standard HEXFETs and 5V on logic level HEXFETs